

### IN THE CLAIMS

Please amend the claims as follows:

1. (Currently Amended) A substrate to mount a die having a plurality of terminals, the substrate comprising:
  - a dielectric core member;
  - a first plurality of dielectric lamination layers on a first side of the core member;
  - a second plurality of conductive layers on the first side of the core member, including a plurality of ball-grid array (BGA) connectors on a first surface of an uppermost one of the second plurality of conductive layers to couple to corresponding terminals of the die;
  - ~~a first number of dielectric lamination layers on a second side of the core member, wherein the first number is less than the first plurality; and~~
  - a single conductive layer ~~second number of conductive layers~~ on the second side of the core member, wherein the single conductive layer comprises a plurality of lands ~~second number is less than the second plurality; and~~
  - a plurality of solder balls, coupled to corresponding ones of the plurality of lands, to couple to corresponding terminals of a receiving substrate.
2. (Previously Presented) A substrate as claimed in claim 1 wherein the dielectric core member comprises material of different dielectric permittivity in comparison to a permittivity of material of dielectric lamination layers of the substrate.
3. (Previously Presented) A substrate as claimed in claim 1, wherein the dielectric core member has a thickness that is thicker than a thickness of at least one dielectric lamination layer, and wherein the dielectric core member includes material of a different dielectric permittivity than that of material of the at least one dielectric lamination layer.
- 4-7. (Canceled)

8. (Currently Amended) A system comprising:
- a die having a plurality of terminals;
  - a receiving substrate having a plurality of terminals;
  - a layered substrate including
    - a dielectric core member;
    - a first plurality of dielectric lamination layers on a first side of the core member;
    - a second plurality of conductive layers on the first side of the core member,
    - including a plurality of ball-grid array connectors on a first surface of an uppermost one of the second plurality of conductive layers, the connectors being coupled to corresponding terminals of the die;
    - ~~a first number of dielectric lamination layers on a second side of the core member,~~
    - ~~wherein the first number is less than the first plurality; and~~
    - a single conductive layer ~~second number of conductive layers~~ on the second side of the core member, wherein the single conductive layer comprises a plurality of lands
    - ~~second number is less than the second plurality; and~~
    - a plurality of solder balls, coupled between ones of the plurality of lands and corresponding terminals of the receiving substrate.
9. (Previously Presented) A system as claimed in claim 8, wherein the dielectric core member comprises material of a different dielectric permittivity in comparison to a permittivity of material of dielectric lamination layers of the substrate.
10. (Currently Amended) A system as claimed in claim 8, wherein the dielectric core member has a thickness that is thicker than a thickness of at least one dielectric lamination layer, and wherein the dielectric core member includes material of a different dielectric permittivity than that of a material of the at least one dielectric lamination layer[[],].
- 11-25. (Canceled)

26. (New) The substrate as claimed in claim 1, wherein the receiving substrate comprises one of an interposer or a motherboard.

27. (New) The system as claimed in claim 8, wherein the receiving substrate comprises one of an interposer or a motherboard.